# 6-Pin DIP Zero-Cross Triac **Driver Output Optocoupler** (250/400 Volt Peak)

# MOC3031M, MOC3032M, MOC3033M, MOC3041M, **MOC3042M, MOC3043M**

### Description

The MOC303XM and MOC304XM devices consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon detector performing the function of a zero voltage crossing bilateral triac driver.

They are designed for use with a triac in the interface of logic systems to equipment powered from 115 VAC lines, such as teletypewriters, CRTs, solid-state relays, industrial controls, printers, motors, solenoids and consumer appliances, etc.

#### **Features**

- Simplifies Logic Control of 115 VAC Power
- Zero Voltage Crossing to Minimize Conducted and Radiated Line
- dv/dt of 2000 V/μs Typical, 1000 V/μs Guaranteed
- Peak Blocking Voltage
  - ◆ 250 V, MOC306xM
  - 400 V, MOC304xM
- Safety and Regulatory Approvals
  - ◆ UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
  - ◆ DIN EN/IEC60747-5-5
- These are Pb-Free Devices

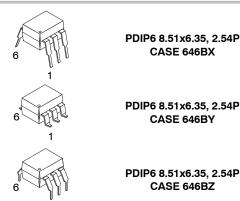
#### **Applications**

- Solenoid/Valve Controls
- Lighting Controls
- Static Power Switches
- AC Motor Drives
- Temperature Controls
- E.M. Contactors
- AC Motor Starters
- Solid State Relays



### ON Semiconductor®

#### www.onsemi.com



#### MARKING DIAGRAM



MOC3031 = Device Number

= DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)

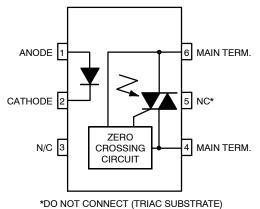
= One-Digit Year Code, e.g., '5' Χ

= Two-Digit Work Week, Ranging from

'01' to '53'

Q = Assembly Package Code

#### **SCHEMATIC**



#### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

**SAFETY AND INSULATION RATINGS** (As per DIN EN/IEC 60747–5–5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.)

Parameter	Characteristics	
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	<150 V <sub>RMS</sub>	I–IV
	<300 V <sub>RMS</sub>	I–IV
Climatic Classification		40/85/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
$V_{PR}$	Input–to–Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with $t_m = 10 \text{ s}$ , Partial Discharge $< 5 \text{ pC}$	1275	V <sub>peak</sub>
	Input–to–Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with $t_m = 1$ s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
$V_{IORM}$	Maximum Working Insulation Voltage	850	$V_{peak}$
$V_{IOTM}$	Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
	External Creepage	≥7	mm
	External Clearance	≥7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥0.5	mm
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	>10 <sup>9</sup>	Ω

# ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Device	Value	Unit
TOTAL DEVIC	E			
T <sub>STG</sub>	Storage Temperature	All	-40 to +150	°C
T <sub>OPR</sub>	Operating Temperature	All	-40 to +85	°C
TJ	Junction Temperature Range	All	-40 to +100	°C
T <sub>SOL</sub>	Lead Solder Temperature	All	260 for 10 seconds	°C
$P_{D}$	Total Device Power Dissipation at 25°C Ambient	All	250	mW
	Derate Above 25°C		2.94	mW/°C
EMITTER				
I <sub>F</sub>	Continuous Forward Current	All	60	mA
V <sub>R</sub>	Reverse Voltage	All	6	V
$P_{D}$	Total Power Dissipation at 25°C Ambient	All	120	mW
	Derate Above 25°C		1.41	mW/°C
DETECTOR				
V <sub>DRM</sub>	Off-State Output Terminal Voltage	MOC3031M MOC3032M MOC3033M	250	٧
		MOC3041M MOC3042M MOC3043M	400	٧
I <sub>TSM</sub>	Peak Non-Repetitive Surge Current (Surge Cycle 60 Hz Sine Wave)	All	1	A <sub>peak</sub>
I <sub>TM</sub>	Peak Repetitive On-State Current	All	100	mA <sub>peak</sub>
P <sub>D</sub>	Total Power Dissipation at 25°C Ambient	All	150	mW
	Derate Above 25°C		1.76	mW/°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C, unless otherwise noted)

ELECTRI	CAL CHARACTERISTICS	(T <sub>A</sub> = 25°C, unless otherwise noted)					
Symbol	Parameter	Test Conditions	Device	Min	Тур	Max	Unit
NDIVIDUA	L COMPONENT CHARACTE	RISTICS					
EMITTER							
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 30 mA	All	-	1.25	1.50	V
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 6 V	All	-	0.01	100	μΑ
DETECTO	R						
I <sub>DRM1</sub>	Peak Blocking Current, Either Direction	V <sub>DRM</sub> = 600 V, I <sub>F</sub> = 0 (Note 1)	All	-	_	100	nA
V <sub>TM</sub>	Peak On-State Voltage, Either Direction	I <sub>TM</sub> = 100 mA peak, I <sub>F</sub> = 0	All	-	1.8	3.0	V
dv/dt	Critical Rate of Rise of Off-State Voltage	I <sub>F</sub> = 0 (Note 2)	All	1000	2000	-	V/μs
TRANSFE	R CHARACTERISTICS						
I <sub>FT</sub>	LED Trigger Current	Main Terminal Voltage = 3 V (Note 3)	MOC3031M MOC3041M	-	_	15	mA
			MOC3032M MOC3042M	-	_	10	
			MOC3033M MOC3043M	-	_	5	
I <sub>H</sub>	Holding Current, Either Direction		All	_	400	-	μΑ
ZERO CR	OSSING CHARACTERISTICS	•	•				
V <sub>IH</sub>	Inhibit Voltage	I <sub>F</sub> = rated I <sub>FT</sub> , MT1-MT2 voltage above which device will not trigger off-state	All	-	-	20	V
I <sub>DRM2</sub>	Leakage in Inhibited State	$I_F$ = rated $I_{FT}$ , rated $V_{DRM}$ off-state	All	_	_	2	mA
ISOLATIO	N CHARACTERISTICS	•	1				-
V <sub>ISO</sub>	Isolation Voltage (Note 4)	t = 1 Minute	All	4170	_	_	VAC <sub>RN</sub>

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Test voltage must be applied within dv/dt rating.
   This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.
- 3. All devices are guaranteed to trigger at an IF value less than or equal to max IFT. Therefore, recommended operating IF lies between max IFT. (15 mA for MOC3031M and MOC3041M, 10 mA for MOC3032M and MOC3042M, 5 mA for MOC3033M and MOC3043M) and absolute maximum I<sub>F</sub> (60 mA).
- 4. Isolation voltage, V<sub>ISO</sub>, is an internal device dielectric breakdown rating. For this test, pins 1 and 2 are common, and pins 4, 5 and 6 are common.

### **TYPICAL PERFORMANCE CURVES**

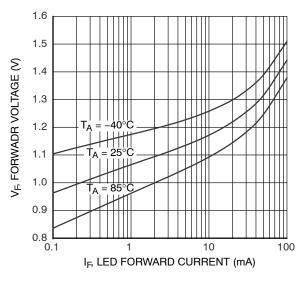


Figure 1. LED Forward Voltage vs. Forward Current

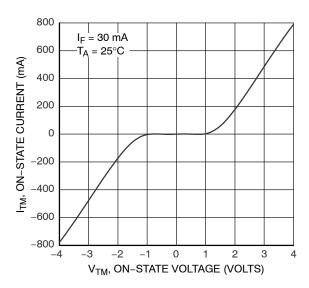


Figure 2. On-State Characteristics

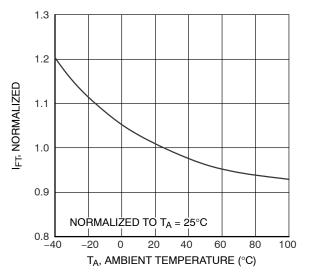


Figure 3. Trigger Current Vs. Temperature

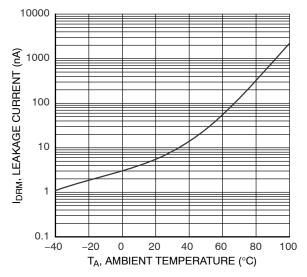


Figure 4. Leakage Current, I<sub>DRM</sub> vs. Temperature

### TYPICAL PERFORMANCE CURVES (Continued)

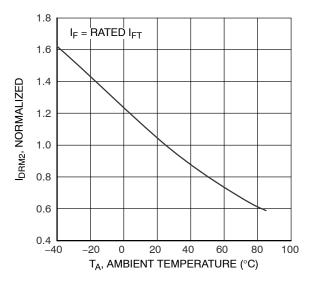


Figure 5. IDRM2 - Leakage in Inhibit State vs. Temperature

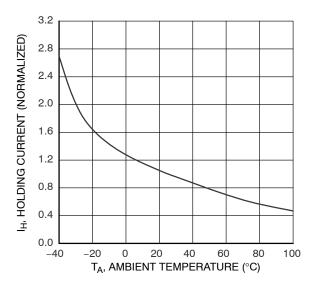


Figure 7. Holding Current, IH vs. Temperature

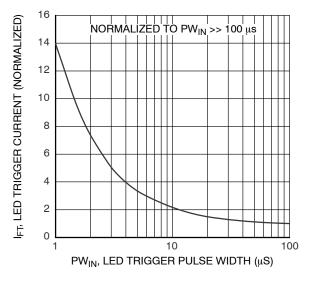


Figure 6. LED Current Required to Trigger vs. LED Pulse Width

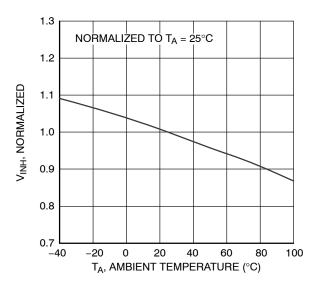


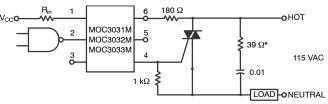
Figure 8. Inhibit Voltage vs. Temperature

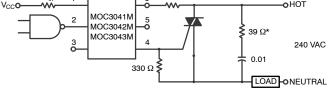
#### APPLICATION INFORMATION

Typical circuit (Figure 9, 10) for use when hot line switching is required. In this circuit the "hot" side of the line is switched and the load connected to the cold or neutral side. The load may be connected to either the neutral or hot line.

 $R_{in}$  is calculated so that  $I_F$  is equal to the rated  $I_{FT}$  of the part, 5 mA for the MOC3033M and MOC3043M, 10 mA for

the MOC3032M and MOC3042M, or 15 mA for the MOC3031M and MOC3041M. The 39 ohm resistor and 0.01  $\mu F$  capacitor are for snubbing of the triac and may or may not be necessary depending upon the particular triac and load used.





\*For highly inductive loads (power factor < 0.5), change this value to 360 ohms.

Figure 9. Hot-Line Switching Application Circuit (MOC3031M, MOC3032M, MOC3033M)

\*For highly inductive loads (power factor < 0.5), change this value to 360 ohms.

Figure 10. Hot-Line Switching Application Circuit
(MOC3041M, MOC3042M, MOC3043M)

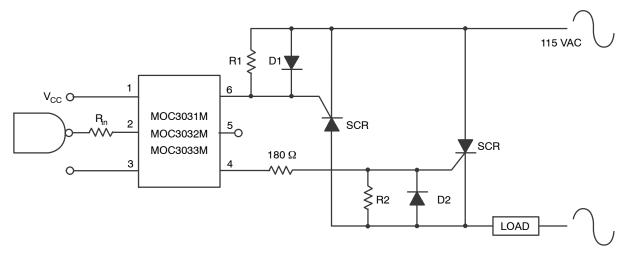


Figure 11. Inverse-Parallel SCR Driver Circuit (MOC3031M, MOC3032M, MOC3033M)

Suggested method of firing two, back-to-back SCR's with a ON Semiconductor triac driver. Diodes can be 1N4001; resistors, R1 and R2, are optional 1 k $\Omega$ .

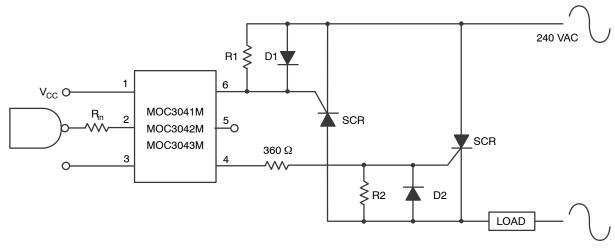


Figure 12. Inverse-Parallel SCR Driver Circuit (MOC3041M, MOC3042M, MOC3043M)

Suggested method of firing two, back-to-back SCR's with a ON Semiconductor triac driver. Diodes can be 1N4001; resistors, R1 and R2, are optional  $330\Omega$ .

NOTE: This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

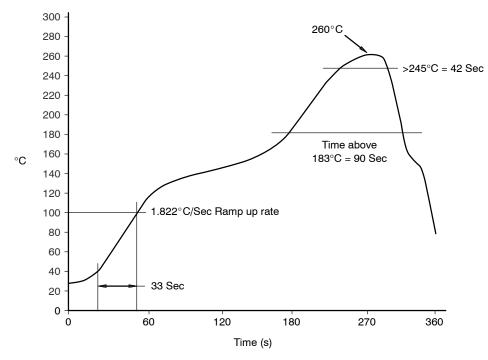


Figure 13. Reflow Profile

### **ORDERING INFORMATION** (Note 5)

Part Number Package		Shipping <sup>†</sup>
MOC3031M	DIP 6-Pin (Pb-Free)	50 Units / Tube
MOC3031SM	SMT 6-Pin (Lead Bend) (Pb-Free)	50 Units / Tube
MOC3031SR2M	SMT 6-Pin (Lead Bend) (Pb-Free)	1000 / Tape & Reel
MOC3031VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option (Pb-Free)	50 Units / Tube
MOC3031SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option (Pb-Free)	50 Units / Tube
MOC3031SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option (Pb-Free)	1000 / Tape & Reel
MOC3031TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option (Pb-Free)	50 Units / Tube

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

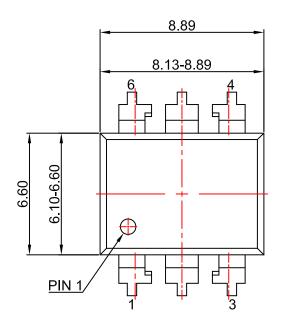
Specifications Brochure, BRD8011/D.

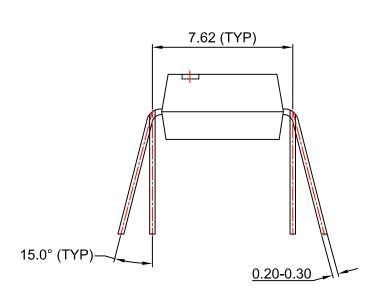
5. The product orderable part number system listed in this table also applies to the MOC3032M, MOC3033M, MOC3041M, MOC3042M, and MOC3043M product families.

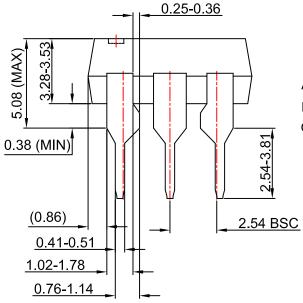


### PDIP6 8.51x6.35, 2.54P CASE 646BX ISSUE O

**DATE 31 JUL 2016** 







### NOTES:

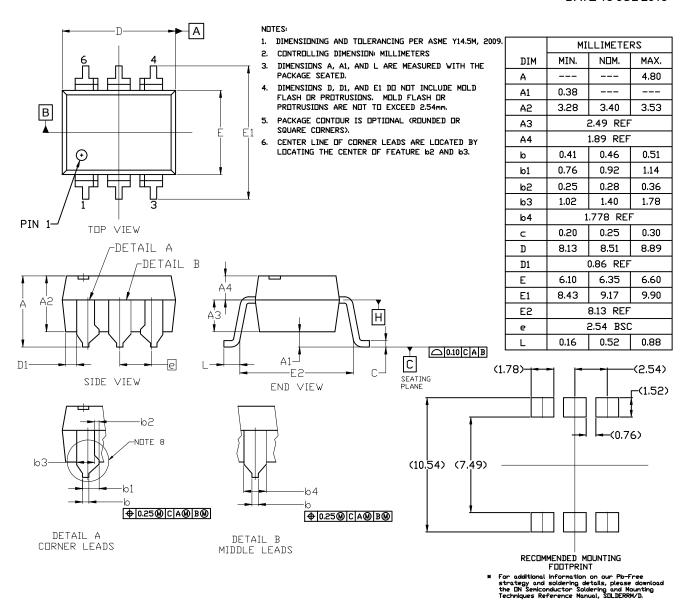
- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DOCUMENT NUMBER:	98AON13449G	Electronic versions are uncontrolled except when accessed directly from the Document Reposito Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	PDIP6 8.51X6.35, 2.54P		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

#### PDIP6 8.51x6.35, 2.54P CASE 646BY ISSUE A

**DATE 15 JUL 2019** 

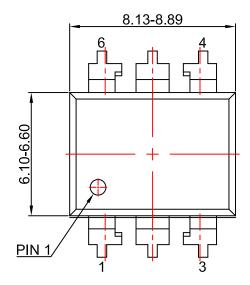


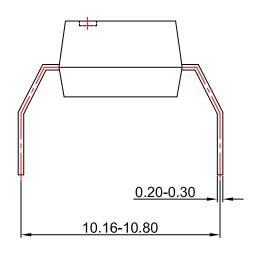
DOCUMENT NUMBER:	98AON13450G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	PDIP6 8.51x6.35, 2.54P		PAGE 1 OF 1	

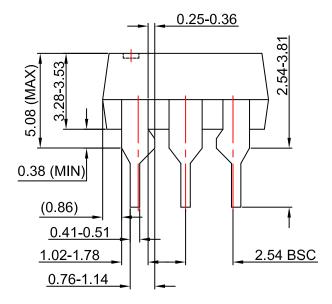
ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

### PDIP6 8.51x6.35, 2.54P CASE 646BZ ISSUE O

**DATE 31 JUL 2016** 







#### NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DOCUMENT NUMBER:	98AON13451G	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	PDIP6 8.51X6.35, 2.54P		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative